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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	418
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Through Hole
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	624-BCCGA
Supplier Device Package	624-CCGA (32.5x32.5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-1cgs624m

Table 2-5 • **Different Components Contributing to the Total Power Consumption in Axcelerator Devices**

Component	Definition	Device Specific Value (in µW/MHz)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

Ptotal = Pdc + Pac

P_{dc} = ICCA * VCCA

P_{ac} = $P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$

P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PCLK = (P4 + P5 * s + P6 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PR-cells = P7 * ms * Fs

ms = the number of R-cells switching at each Fs cycle

Fs = the clock frequency

PC-cells = P8 * mc * Fs

mc = the number of C-cells switching at each Fs cycle

Fs = the clock frequency

Pinputs = P9 * pi * Fpi

pi = the number of inputs

F_{pi} = the average input frequency

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

T_J = Junction Temperature = $\Delta T + T_a$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$\Delta T = \theta_{ja} * P$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (°C) - \text{Max. ambient temp. } (°C)}{\theta_{ja}(°C/W)} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\ W$$

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

***Table 2-57* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)
1.2 – 0.125	1.2 + 0.125	1.2

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-58* • LVDS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVDS Output Module Timing								
t_{DP}	Input Buffer		1.80		2.05		2.41	ns
t_{PY}	Output Buffer		2.32		2.64		3.11	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

The ClockTileDist Cluster contains an HCLKMux (HM) module for each of the four HCLK trees and a CLKMux (CM) module for each of the CLK trees. The HCLK branches then propagate horizontally through the middle of the core tile to HCLKColDist (HD) modules in every SuperCluster column. The CLK branches propagate vertically through the center of the core tile to CLKRowDist (RD) modules in every SuperCluster row. Together, the HCLK and CLK branches provide for a low-skew global fanout within the core tile (Figure 2-40 and Figure 2-41).

Figure 2-40 • **CTD, CD, and HD Module Layout**

Figure 2-41 • **HCLK and CLK Distribution within a Core Tile**

PLL Configurations

The following rules apply to the different PLL inputs and outputs:

Reference Clock

The RefCLK can be driven by (Figure 2-50):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. CLK1 output of an adjacent PLL
3. [H]CLKxP (single-ended or voltage-referenced)
4. [H]CLKxP/[H]CLKxN pair (differential modes like LVPECL or LVDS)

Feedback Clock

The feedback clock can be driven by (Figure 2-51 on page 2-78):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. External [H]CLKxP/N I/O pad(s) from the adjacent PLL cell
3. An internal signal from the PLL block

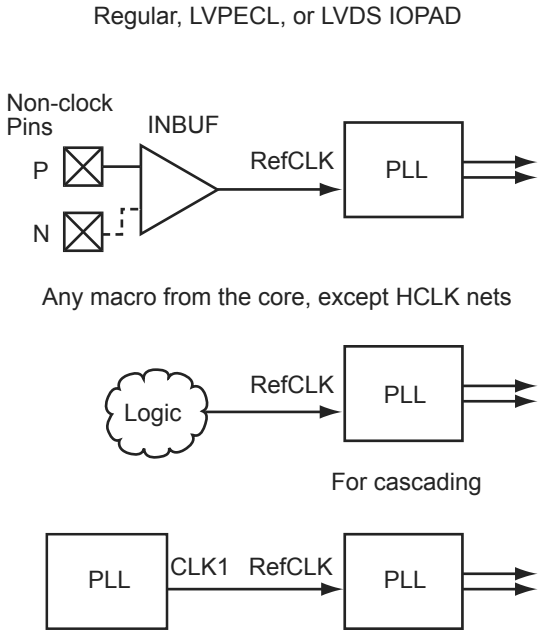


Figure 2-50 • **Reference Clock Connections**

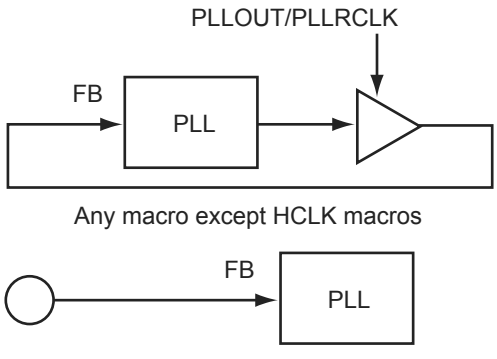


Figure 2-51 • **Feedback Clock Connections**

Special PLL Macros

Table 2-84 shows the macros used to connect the RefCLK input and CLK1 and CLK2 outputs using the different routing resources.

***Table 2-84* • PLL Special Macros**

Macro Name	Usage
PLLINT	Connects RefCLK to a regular routed net or a pad.
PLLRCLK	Connects CLK1 or CLK2 to the CLK network.
PLLHCLK	Connects CLK1 or CLK2 to the HCLK network.
PLLOUT	Connects CLK1 or CLK2 to a regular routed net.

***Table 2-85* • Electrical Specifications**

Parameter	Value	Notes
Frequency Ranges		
Reference Frequency (min.)	14 MHz	Lowest input frequency
Reference Frequency (max.)	200 MHz	Highest input frequency
OSC Frequency (min.)	20 MHz	Lowest output frequency
OSC Frequency (max.)	1 GHz	Highest output frequency
Jitter		
Long-Term Jitter (max.)	1%	Percentage of period, low reference clock frequencies
Long-Term Jitter (max.)	100ps	High reference clock frequencies
Short-Term Jitter (max.)	50ps+1%	Percentage of output frequency
Acquisition Time (lock) from Cold Start		
Acquisition Time (max.)*	400 cycles	Period of low reference clock frequencies
Acquisition Time (max.)*	1.5 µs	High reference clock frequencies
Power Consumption		
Analog Supply Current (low freq.)	200 µA	Current at minimum oscillator frequency
Analog Supply Current (high freq.)	200 µA	Frequency-dependent current
Digital Supply Current (low freq.)	0.5 µA/MHz	Current at maximum oscillator frequency, unloaded
Digital Supply Current (high freq.)	1 µA/MHz	Frequency-dependent current
Duty Cycle		
Minimum Output Duty Cycle	45%	
Maximum Output Duty Cycle	55%	

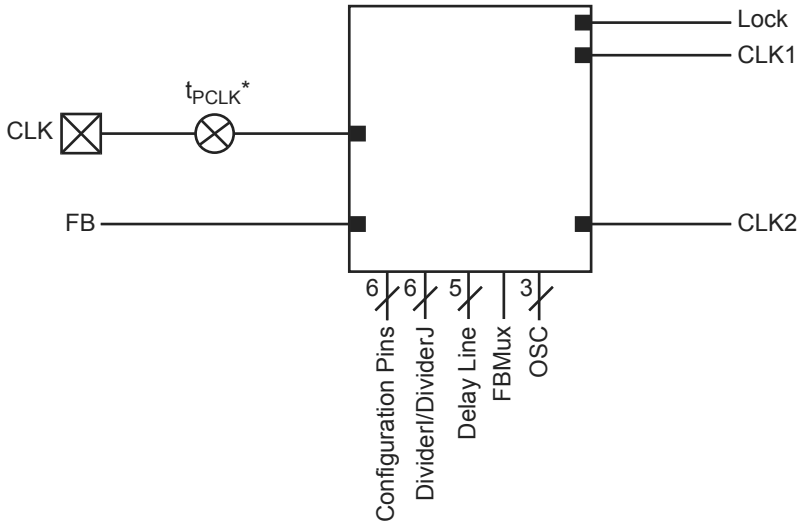
*Note: *The lock bit remains Low until RefCLK reaches the minimum input frequency.*

User Flow

There are two methods of including a PLL in a design:

- The recommended method of using a PLL is to create custom PLL blocks using Microsemi's macro generator, SmartGen, that can be instantiated in a design.
- The alternative method is to instantiate one of the generic library primitives (PLL or PLLFB) into either a schematic or HDL netlist, using inverters for polarity control and tying all unused address and data bits to ground.

Timing Model



Note: t_{PCLK} is the delay in the clock signal

Figure 2-52 • **PLL Model**

BG729	
AX1000 Function	Pin Number
GND	B27
GND	B3
GND	C1
GND	C2
GND	C25
GND	C26
GND	C27
GND	C3
GND	E27
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17

BG729	
AX1000 Function	Pin Number
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND/LP	J8
NC	U3
PRA	J14
PRB	D14
PRC	V14
PRD	AB14
TCK	E4
TDI	D4
TDO	J9
TMS	H8
TRST	E3
VCCA	AA21
VCCA	AD5
VCCA	E1
VCCA	G22
VCCA	K10

BG729	
AX1000 Function	Pin Number
VCCA	K11
VCCA	K17
VCCA	K18
VCCA	L10
VCCA	L18
VCCA	U10
VCCA	U18
VCCA	V10
VCCA	V11
VCCA	V17
VCCA	V18
VCCPLA	A13
VCCPLB	J13
VCCPLC	B15
VCCPLD	C15
VCCPLE	AG14
VCCPLF	AF14
VCCPLG	AB13
VCCPLH	AG13
VCCDA	A11
VCCDA	AB12
VCCDA	AC12
VCCDA	AC25
VCCDA	AD16
VCCDA	AD17
VCCDA	E16
VCCDA	E2
VCCDA	E24
VCCDA	F12
VCCDA	F16
VCCDA	F7
VCCDA	K14
VCCDA	P10
VCCDA	P18
VCCDA	W14
VCCDA	W9
VCCIB0	A4

FG324	
AX125 Function	Pin Number
Bank 0	
IO00NB0F0	C5
IO00PB0F0	C4
IO01NB0F0	A3
IO01PB0F0	A2
IO02NB0F0	C7
IO02PB0F0	C6
IO03NB0F0	B5
IO03PB0F0	B4
IO04NB0F0	A5
IO04PB0F0	A4
IO05NB0F0	A7
IO05PB0F0	A6
IO06NB0F0	B7
IO06PB0F0	B6
IO07NB0F0/HCLKAN	C9
IO07PB0F0/HCLKAP	C8
IO08NB0F0/HCLKBN	B10
IO08PB0F0/HCLKBP	B9
Bank 1	
IO09NB1F1/HCLKCN	D11
IO09PB1F1/HCLKCP	D10
IO10NB1F1/HCLKDN	C12
IO10PB1F1/HCLKDP	C11
IO11NB1F1	A15
IO11PB1F1	A14
IO12NB1F1	B14
IO12PB1F1	B13
IO13NB1F1	A17
IO13PB1F1	A16
IO14NB1F1	D13
IO14PB1F1	D12
IO15NB1F1	C14
IO15PB1F1	C13
IO16NB1F1	B16

FG324	
AX125 Function	Pin Number
IO16PB1F1	C15
IO17NB1F1	E14
IO17PB1F1	E13
Bank 2	
IO18NB2F2	G14
IO18PB2F2	F14
IO19NB2F2	D16
IO19PB2F2	D15
IO20NB2F2	C18
IO20PB2F2	B18
IO21NB2F2	D17
IO21PB2F2	C17
IO22NB2F2	F17
IO22PB2F2	E17
IO23NB2F2	G16
IO23PB2F2	F16
IO24NB2F2	E18
IO24PB2F2	D18
IO25NB2F2	G18
IO25PB2F2	F18
IO26NB2F2	H17
IO26PB2F2	G17
IO27NB2F2	J16
IO27PB2F2	H16
IO28NB2F2	J18
IO28PB2F2	H18
IO29NB2F2	K17
IO29PB2F2	J17
Bank 3	
IO30NB3F3	N18
IO30PB3F3	M18
IO31NB3F3	L18
IO31PB3F3	K18
IO32NB3F3	L16
IO32PB3F3	L17

FG324	
AX125 Function	Pin Number
IO33NB3F3	R18
IO33PB3F3	P18
IO34NB3F3	N15
IO34PB3F3	M15
IO35NB3F3	M16
IO35PB3F3	M17
IO36NB3F3	P16
IO36PB3F3	N16
IO37NB3F3	R17
IO37PB3F3	P17
IO38NB3F3	N14
IO38PB3F3	M14
IO39NB3F3	U18
IO39PB3F3	T18
IO40NB3F3	R16
IO40PB3F3	T17
IO41NB3F3	P13
IO41PB3F3	P14
Bank 4	
IO42NB4F4	T13
IO42PB4F4	T14
IO43NB4F4	U15
IO43PB4F4	T15
IO44NB4F4	U13
IO44PB4F4	U14
IO45NB4F4	V15
IO45PB4F4	V16
IO46NB4F4	V13
IO46PB4F4	V14
IO47NB4F4	V12
IO47PB4F4	U12
IO48NB4F4	V10
IO48PB4F4	V11
IO49NB4F4/CLKEN	T10
IO49PB4F4/CLKEP	T11

FG484	
AX500 Function	**Pin Number**
IO163NB7F15	G5
IO163PB7F15	G6
IO164NB7F15	D1
IO164PB7F15	E1
IO165NB7F15	F4
IO165PB7F15	G4
IO166NB7F15	D2
IO166PB7F15	E2
IO167NB7F15	F5
IO167PB7F15	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19

FG484	
AX500 Function	**Pin Number**
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18

FG484	
AX500 Function	**Pin Number**
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	AB8
NC	AB16
NC	C10
NC	C11
NC	C14
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10

FG676	
AX1000 Function	**Pin Number**
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	**Pin Number**
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	**Pin Number**
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896	
AX1000 Function	Pin Number
NC	K1
NC	K2
NC	L30
NC	M30
NC	N29
NC	T1
NC	U1
NC	W30
NC	Y1
NC	Y2
NC	Y30
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11

FG896	
AX1000 Function	Pin Number
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCCDA	AD24
VCCDA	AD7
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18

FG896	
AX1000 Function	Pin Number
VCCDA	AF19
VCCDA	C13
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F26
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21

FG896	
AX2000 Function	Pin Number
IO65PB1F6	H20
IO66NB1F6	B23
IO66PB1F6	B21
IO67NB1F6	H21
IO67PB1F6	G21
IO68NB1F6	D22
IO68PB1F6	C22
IO69NB1F6	A25
IO69PB1F6	A24
IO70NB1F6	F22
IO70PB1F6	E22
IO71NB1F6	F21
IO71PB1F6	E21
IO73NB1F6	C24
IO73PB1F6	C23
IO74NB1F6	D24
IO74PB1F6	D23
IO75NB1F6	H23
IO75PB1F6	H22
IO76NB1F7	B25
IO76PB1F7	B24
IO78NB1F7	B26
IO78PB1F7	A26
IO79NB1F7	F23
IO79PB1F7	E23
IO80NB1F7	D25
IO80PB1F7	C25
IO81NB1F7	G23
IO81PB1F7	G22
IO82NB1F7	B27
IO82PB1F7	A27
IO83NB1F7	F24
IO83PB1F7	E24
IO84NB1F7	D26
IO84PB1F7	C26

FG896	
AX2000 Function	Pin Number
IO85NB1F7	F25
IO85PB1F7	E25
Bank 2	
IO86NB2F8	G26
IO86PB2F8	G25
IO87NB2F8	K23
IO87PB2F8	J23
IO88NB2F8	J24
IO88PB2F8	H24
IO89NB2F8	E29
IO89PB2F8	D29
IO90NB2F8	F27
IO90PB2F8	E27
IO91NB2F8	H26
IO91PB2F8	H25
IO92NB2F8	G28
IO92PB2F8	F28
IO93NB2F8	J26
IO93PB2F8	J25
IO94NB2F8	H27
IO94PB2F8	G27
IO95NB2F8	H29
IO95PB2F8	G29
IO96NB2F9	G30
IO96PB2F9	F30
IO97NB2F9	K25
IO97PB2F9	K24
IO98NB2F9	J28
IO98PB2F9	H28
IO99NB2F9	L23
IO99PB2F9	L24
IO100NB2F9	K27
IO100PB2F9	J27
IO101PB2F9	J30
IO102NB2F9	E30

FG896	
AX2000 Function	Pin Number
IO102PB2F9	D30
IO103NB2F9	L26
IO103PB2F9	K26
IO104NB2F9	F29
IO105NB2F9	M25
IO105PB2F9	L25
IO106NB2F9	K30
IO106PB2F9	K29
IO107NB2F10	M23
IO107PB2F10	M24
IO109NB2F10	M27
IO109PB2F10	L27
IO110NB2F10	M28
IO110PB2F10	L28
IO111NB2F10	N22
IO111PB2F10	N23
IO112NB2F10	M29
IO112PB2F10	L29
IO113NB2F10	N26
IO113PB2F10	M26
IO114NB2F10	M30
IO114PB2F10	L30
IO115NB2F10	N28
IO115PB2F10	N27
IO117NB2F10	N25
IO117PB2F10	N24
IO118NB2F11	N29
IO119NB2F11	P22
IO119PB2F11	P23
IO121NB2F11	P25
IO121PB2F11	P24
IO122NB2F11	P28
IO122PB2F11	P27
IO123NB2F11	R26
IO123PB2F11	P26

FG896	
AX2000 Function	Pin Number
GND	W19
GND	Y11
GND	Y20
GND/LP	E4
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20

FG896	
AX2000 Function	Pin Number
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCDA	AD24
VCCDA	AD7
VCCDA	AE15
VCCDA	AE16
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18
VCCDA	AF19
VCCDA	AH27
VCCDA	AH4
VCCDA	C13
VCCDA	C27
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F15
VCCDA	F16
VCCDA	F26

FG896	
AX2000 Function	Pin Number
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21
VCCIB2	L22
VCCIB2	M21
VCCIB2	M22
VCCIB2	N21
VCCIB2	P21
VCCIB2	R21
VCCIB3	AA22
VCCIB3	AH29

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

FG1152	
AX2000 Function	**Pin Number**
IO207PB4F19	AL20
IO208NB4F19	AG19
IO208PB4F19	AF19
IO209NB4F19	AN18
IO209PB4F19	AP18
IO210NB4F19	AE19
IO210PB4F19	AD19
IO211NB4F19	AL18
IO211PB4F19	AM18
IO212NB4F19/CLKEN	AJ20
IO212PB4F19/CLKEP	AK20
IO213NB4F19/CLKFN	AJ18
IO213PB4F19/CLKFP	AJ19
Bank 5	
IO214NB5F20/CLKGN	AJ16
IO214PB5F20/CLKGP	AJ17
IO215NB5F20/CLKHN	AJ15
IO215PB5F20/CLKHP	AK15
IO216NB5F20	AD16
IO216PB5F20	AE17
IO217NB5F20	AM17
IO217PB5F20	AL17
IO218NB5F20	AG16
IO218PB5F20	AF16
IO219NB5F20	AM16
IO219PB5F20	AL16
IO220NB5F20	AP16
IO220PB5F20	AN16
IO221NB5F20	AN15
IO221PB5F20	AP15
IO222NB5F20	AD15
IO222PB5F20	AE16
IO223NB5F21	AL14
IO223PB5F21	AL15
IO224NB5F21	AN14

FG1152	
AX2000 Function	**Pin Number**
IO224PB5F21	AP14
IO225NB5F21	AK13
IO225PB5F21	AK14
IO226NB5F21	AE15
IO226PB5F21	AF15
IO227NB5F21	AG14
IO227PB5F21	AG15
IO228NB5F21	AJ13
IO228PB5F21	AJ14
IO229NB5F21	AM13
IO229PB5F21	AM14
IO230NB5F21	AE14
IO230PB5F21	AF14
IO231NB5F21	AN12
IO231PB5F21	AP12
IO232NB5F21	AG13
IO232PB5F21	AH13
IO233NB5F21	AL12
IO233PB5F21	AL13
IO234NB5F21	AE13
IO234PB5F21	AF13
IO235NB5F22	AN11
IO235PB5F22	AP11
IO236NB5F22	AM11
IO236PB5F22	AM12
IO237NB5F22	AJ11
IO237PB5F22	AJ12
IO238NB5F22	AH11
IO238PB5F22	AH12
IO239NB5F22	AK10
IO239PB5F22	AK11
IO240NB5F22	AE12
IO240PB5F22	AF12
IO241NB5F22	AN10
IO241PB5F22	AP10

FG1152	
AX2000 Function	**Pin Number**
IO242NB5F22	AG11
IO242PB5F22	AG12
IO243NB5F22	AL9
IO243PB5F22	AL10
IO244NB5F22	AM8
IO244PB5F22	AM9
IO245NB5F23	AH10
IO245PB5F23	AJ10
IO246NB5F23	AF10
IO246PB5F23	AF11
IO247NB5F23	AJ9
IO247PB5F23	AK9
IO248NB5F23	AN7
IO248PB5F23	AP7
IO249NB5F23	AL7
IO249PB5F23	AL8
IO250NB5F23	AE10
IO250PB5F23	AE11
IO251NB5F23	AK8
IO251PB5F23	AJ8
IO252NB5F23	AH8
IO252PB5F23	AH9
IO253NB5F23	AN6
IO253PB5F23	AP6
IO254NB5F23	AG9
IO254PB5F23	AG10
IO255NB5F23	AJ7
IO255PB5F23	AK7
IO256NB5F23	AL6
IO256PB5F23	AM6
Bank 6	
IO257NB6F24	AG6
IO257PB6F24	AH6
IO258NB6F24	AD9
IO258PB6F24	AE9

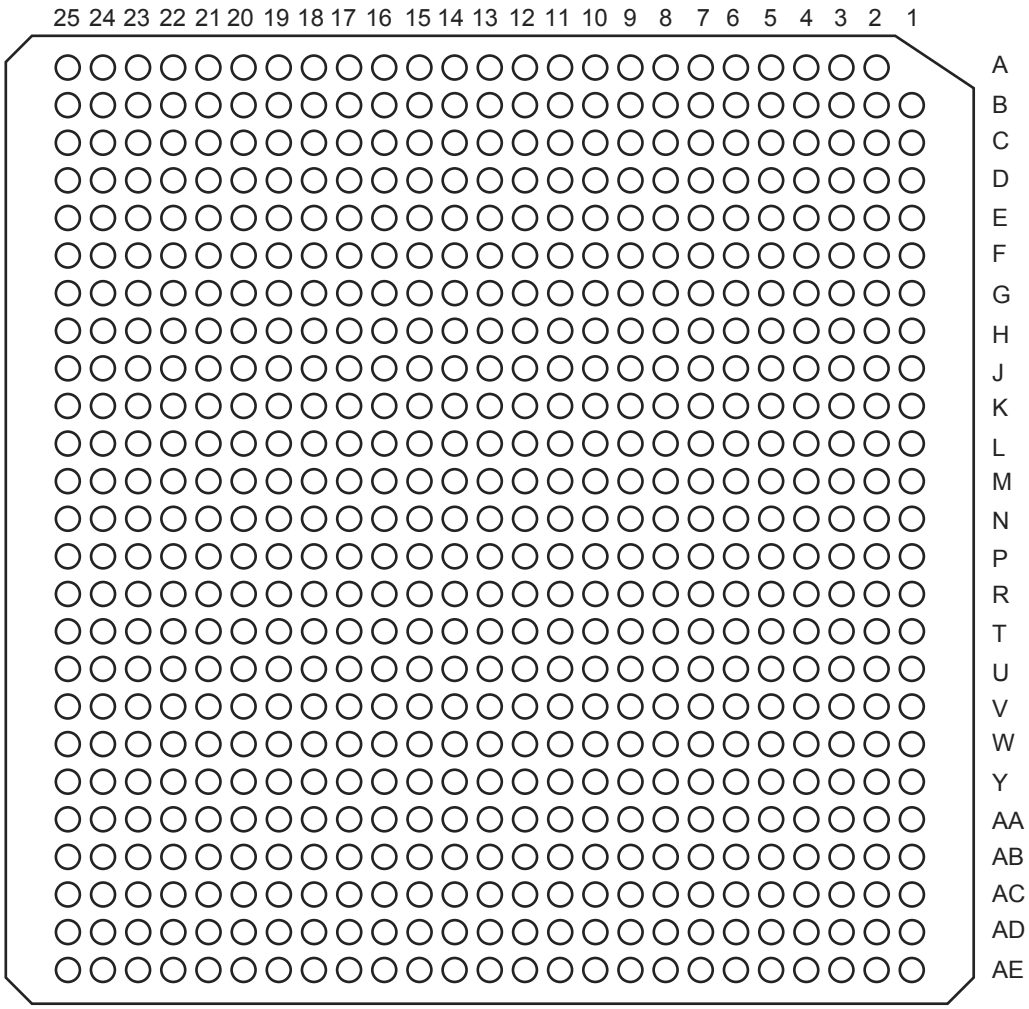
FG1152	
AX2000 Function	**Pin Number**
VCOMPLD	K18
VCOMPLE	AH19
VCOMPLF	AF18
VCOMPLG	AH16
VCOMPLH	AD17
VPUMP	J26

CQ256	
AX2000 Function	Pin Number
IO242NB5F22	74
IO242PB5F22	75
IO243NB5F22	70
IO243PB5F22	71
IO244NB5F22	68
IO244PB5F22	69
Bank 6	
IO257PB6F24	60
IO258NB6F24	58
IO258PB6F24	59
Bank 6	
IO279NB6F26	56
IO279PB6F26	57
IO280NB6F26	52
IO280PB6F26	53
IO281NB6F26	50
IO281PB6F26	51
IO282NB6F26	46
IO282PB6F26	47
IO284NB6F26	44
IO284PB6F26	45
IO285NB6F26	40
IO285PB6F26	41
IO286NB6F26	38
IO286PB6F26	39
IO287NB6F26	34
IO287PB6F26	35
Bank 7 9	
IO310NB7F29	30
IO310PB7F29	31
IO311NB7F29	26
IO311PB7F29	27
IO312NB7F29	24
IO312PB7F29	25
IO315NB7F29	20

CQ256	
AX2000 Function	Pin Number
IO315PB7F29	21
IO316NB7F29	18
IO316PB7F29	19
IO317NB7F29	14
IO317PB7F29	15
IO318NB7F29	12
IO318PB7F29	13
IO320NB7F29	8
IO320PB7F29	9
Bank 7	
IO341NB7F31	6
IO341PB7F31	7
Dedicated I/O	
GND	1
GND	5
GND	11
GND	17
GND	23
GND	29
GND	33
GND	37
GND	43
GND	49
GND	55
GND	62
GND	64
GND	65
GND	73
GND	79
GND	85
GND	91
GND	97
GND	103
GND	109
GND	115

CQ256	
AX2000 Function	Pin Number
GND	121
GND	128
GND	129
GND	132
GND	139
GND	145
GND	151
GND	157
GND	161
GND	165
GND	171
GND	177
GND	183
GND	190
GND	192
GND	193
GND	201
GND	207
GND	213
GND	219
GND	225
GND	231
GND	239
GND	245
GND	256
PRA	227
PRB	226
PRC	99
PRD	98
TCK	253
TDI	252
TDO	250
TMS	254
TRST	255
VCCA	3

CG624



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

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